"PRECISION, INNOVATION & DEDICATION. EVERY MISSION, EVERY TIME."

## **Mission Statement**

Advanced Mission Partners is committed to operating as a trusted strategic partner focused on the design, manufacturing, and testing of high-quality electronic subassemblies and systems for all applications.

### **Overview**

Advanced Mission Partners is dedicated to delivering low-cost, high reliability solutions to our customers. Our infrastructure is designed to support both highly complex mission-critical hardware as well as quick turn R&D efforts. The manufacturing team leveraged over 150 years of combined experience and lessons learned to build a 32,000 sqft state of the art facility. Our technical staff and leadership are dedicated to delivering on customer commitments while maintaining a strong focus on reducing waste and inefficiency.

# **Core Capabilities**

#### **Engineering**

- · Systems Engineering
  - Requirements Development and Management
  - Verification and Validation
- Electrical, Electronic and Electromechanical (EEE) Parts Selection, Procurement and Analysis
- Electrical and Power Systems
   Design
- Design For Manufacturability Services (DFM)
- Flight and Ground Systems Integration
- EGSE/STE Design, Development and Maintenance

#### **Electronics Manufacturing**

- Manufacturing of Printed Circuit Board (PCB) size up to 20" x 20"
- Quick turnaround & R & D prototypes
- Component placements as small as 0.008" X 0.004" with an accuracy of ±1.4 mil
- High-resolution vision system capable of measuring BGA balls as small as 4 mil in diameter with a 10 mil pitch
- Supportability of 224 unique components in one set up (based on component size) and 30 matrix tray components
- Intelligent electronic feeders
- Traceability from the Circuit Card
   Assembly (CCA) back to the original reel

#### **Program Management**

- Concept to delivery PM services
- Expert planning, execution, and oversight
- Proactive risk analysis and mitigation
- Consistent and timely communication
- On time delivery and budget tracking
- Strategic resource monitoring and allocation
- Stakeholder engagement and relationship management



## **Machine Specs**

Machine	Capabilities
SQ3000 Multi Function 3D AOI	<ul> <li>3D AOI, SPI and PWB CMM capability</li> <li>High-Resolution sensor capable of inspecting component sizes as small as .008" x .004"</li> <li>Gage R&amp;R accuracy &lt;10% @ ±3σ (±80 µm process tolerance)</li> <li>Provides 3D measurements for solder, component height, and component body/lead coplanarity</li> </ul>
JUKI RS-1RXL Pick and Place Equipment	<ul> <li>Support for PCB sizes up to 25" x 25"</li> <li>Placement accuracy ± 1.37 mils (35 µm)</li> <li>27mm vision camera for BGA and leaded component placement</li> <li>BGA ball size 4 mils minimum</li> <li>BGA ball pitch 10 mils minimum</li> <li>QFP lead size 8 mils x 5 mils minimum</li> <li>QFP lead pitch 12 mils minimum</li> <li>Smallest component size 008004 Imperial (0201 Metric)</li> <li>Capacity for 224 unique components (8mm reels) and 30 matrix trays</li> <li>Combined throughput of 58,000 CPH per IPC9850</li> <li>Intelligent feeders with full traceability of component placements</li> </ul>
Heller 1913 MK5 Reflow Oven	<ul> <li>26 Independent temperature-controlled heating zones</li> <li>3 Top side cooling zones</li> <li>Zone temperature stability ± 1C</li> <li>Center board support</li> <li>KIC SPS wireless smart profiler</li> <li>KIC PROBOT automatic profile capture</li> <li>Oven air temperature recorded for each CCA real time. Temperatures are compared to previous known good profiles to validate successful reflow.</li> </ul>

## **Past Performance & Teammates**





















# **Company Details**

UEI: RZJNZDE9K255 NAICS Code: 334418 Cage Code: 9TX45

# **Registrations/Certifications**

- IPC-600
- IPC-610
- IPC-620
- IPC-7711/7721
- ANSI S20.20
- J-STD-001 w/ Space Addendum

# **Awards/Recognition**





- Work-Life Flexibility
- Compensation and Benefits
- Robert H. Goddard Awards



